



**SUNEA**

# IPC-8系列无铅热风回流炉

Lead-Free Hot Air Reflow System



模块化 高性能 人性化

MODULARIZATION  
HIGH PERFORMANCE  
HUMANIZATION

## 新一代高端回流炉

New generation advanced reflow system

服务热线：400-019-9680

### 日东科技(控股)有限公司

地址：香港九龙官塘道436-446号官塘工业中心第四期一楼H室  
电话：(852) 2342 7788 传真：(852) 2343 3120

上海办事处：上海市普陀区曹杨路362弄15号金阳大厦11层01-03室  
电话：021-62445868 传真：021-62052406 邮编：200063

广州办事处：广州市天河区中山大道中258号南国嘉园苹果城A座1806室  
电话：020-82562486 传真：020-82562726 邮编：510660

北京办事处：北京市海淀区上地西里颂芳园3号楼2单元102室  
电话：010-62978227 82781265 传真：010-62978817

西安办事处：西安市太白南路263号新一代国际公寓B座601室  
电话：029-88219601 88219591 传真：029-88210427

成都办事处：成都市一环路东五段108号东恒国际2栋2区604室  
电话：028-84400193 传真：028-84400920 邮编：610066

重庆办事处：重庆市高新区科园二路7号彩甸苑6号楼14-2室  
电话：023-68185739 传真：023-68185739 邮编：400039

合肥办事处：合肥市蜀山区黄山路499号建业领翔花园3栋2307室  
电话：0551-65670627 邮编：230000

东莞办事处：东莞市寮步镇凤临花语岸二栋2单元3楼304室  
电话：0769-81779716 邮编：523000

武汉办事处：武汉市东湖开发区关山大道218号保利花园D栋1802室  
电话：027-87425231 传真：027-87425231 邮编：430074

www.suneast.com.cn

E-mail: market@suneast.com.cn

资料仅供参考，一切以合同所定内容为准  
本产品资料更改恕不另行通知

### 日东电子科技(深圳)有限公司

地址：深圳市宝安区福永镇白石厦工业东区安全路日东工业园  
电话：(86-755) 27330313 传真：(86-755) 27330323 邮编：518103

厦门办事处：厦门市湖里区兴隆路500号206A室  
电话：0592-5779612 传真：0592-5779613 邮编：361006

杭州办事处：杭州市江干区凤起东路42号广厦大厦1308室  
电话：0571-86028240 传真：0571-86028040 邮编：310020

苏州办事处：苏州市姑苏区杨枝塘路城湾地区158号冠南苑4栋406室  
电话：0512-62515751 传真：0512-62515751 邮编：215125

南京办事处：南京市江宁区双龙大道1251号双龙苑1栋407室  
电话：025-52079355 传真：025-52079355 邮编：210011

青岛办事处：青岛市市北区新隆一路新隆家园7号楼5单元502室  
电话：0532-83743079 传真：0532-83743079 邮编：266000

宁波办事处：宁波市高新区江南一品花园大厦255号1008室  
电话：0574-87499185 邮编：315040

郑州办事处：郑州市中原区锦艺国际花都10号楼2单元2803室  
电话：0731-55686590 邮编：450000

济南办事处：山东省济南市历城区辛甸花园1号楼5单元701室  
电话：15811321721 邮编：250100

南昌办事处：南昌市青山湖区洪都北大道青山湖香寓1614室  
电话：0791-88595059 传真：0791-88595059 邮编：330000



**SUNEA**  
Since 1984

国家高新技术企业

香港联交所主板上市 股票代码：0365.HK

Listed on mainboard of stock exchange Of Hong Kong Stock code:0365.HK

# 公司简介

Company profile

日东于1984年成立于香港，以自动化焊接设备起家，经过30年的辛勤耕耘，现已发展成为实力强大的集团公司，2000年10月16日在香港主板上市，命名为“日东科技（控股）有限公司”，总部设在香港，在深圳自设工业园，总建筑面积6万多平方米。公司现配备有现代化设施，集研发、设计、生产、销售和服务为一体。集团现有在职员工1300余人，其中专业工程设计人员300多人，具有雄厚的研发、生产加工能力。

随着企业的不断发展壮大，日东集团逐步实施品牌化战略，以高科技产业为发展目标，提高核心竞争力，并不断引进新的投资。集团下属设有日东电子发展（深圳）有限公司、日东电子科技（深圳）有限公司、富运精密设备（深圳）有限公司、天力精密系统（深圳）有限公司四家子公司，主营业务包括软件开发、自动印刷机、贴片机、回流焊、波峰焊、AOI、X-Ray、焊线机、武藏点胶机、COG、EPSON机械手、物流仓储设备、自动化生产设备、清洗设备、LED模组生产线、汽车自动化生产线装备、FPD平板显示以及精密设备ODM、产品广泛应用于汽车电子、电子机械、家用电器、LED、LCD、医疗、交通、通讯、物流以及金融等领域。

Sun East was founded in Hong Kong in 1984, started from manufacturing automotive soldering equipment. After 30 years of hard work, Sun East had grown to be a powerful group company. Sun East was listed in the main board of Hong Kong Stock Market as SUN EAST TECHNOLOGY (HOLDING) CO., LTD on 16<sup>th</sup> Oct, 2000. The headquarter is located in Hong Kong, and the manufacturing site set up in Shenzhen. The Shenzhen manufacturing site is more than 60000 square meters, integrating R & D, design, production, sale and service into one. The group has over 1300 employees, including over 300 professional engineers and technicians to support Sun East's strong R & D and production capability. As the Sun East Group continues to grow, it gradually focus more on its branding strategy, developing in the high technology industry, constantly improving enterprise's core competitiveness and introduce new investment projects. There are four subsidiary companies under the Sun East group which are the Sun East Electronic Development (Shenzhen) Co.,Ltd., Sun East Technology (Shenzhen) Co., Ltd., Frontier Precision System (Shenzhen) Co., Ltd. and Fureach Precision Equipment (Shenzhen) Co., Ltd. The group's main businesses included software development, SMT equipment, wave soldering machine, AOI, wire bonder, X-Ray, COB, COG, logistics equipment, automated production line, automotive production lines, solar photovoltaic equipment, environment-friendly cleaning equipment, FPD flat display and precision equipment ODM. The products are used widely in the automotive equipment, electro machine, household appliances, LED, LCD, medicine, transportation, communication, logistics and finance industries.



# 产品目录

Catalog

新技术展示 New technology display	01
操作系统 Design patent of flux management system	01
选配项目 Option	01
其他保护装置及功能 Others protection device&function	02
产品特点 Product features	02
规格 Specifications	03
整体示意图 Whole sketch	05
整线二合一示意图 Possible System Configuration	05
IPC-8性能测试及设备方法 IPC-8 performance test device and method	06-09
一、PCBA的横截面的温差分析 Temperature difference analyses of PCBA cross section	06
二、热效能均衡度评测 Evaluation of heat efficiency equality	07
三、热效率评测 Heat efficiency evaluation	08
四、热补偿能力评测 Evaluation of Heat compensation ability	08
五、热稳定性评测 Heat stability evaluation	09
综合指标水平 Aggregative indicator lever	09
Esamber回焊炉性能测试仪 Esamber Reflow Explorer	10
Esamber R <sup>®</sup> 温度曲线测试仪 Esamber R <sup>®</sup> Profiler	10
我们的优势 Our strength	11
荣誉 Achievements	12

## NEW TECHNOLOGY DISPLAY

## 新技术展示

IPC-8(intelligent process control-基于生产工艺控制) 基于Genesis 8系列整体设计, 采用先进的生产工艺控制, 以IPC-985X(回流焊系统的评测)为检验标准, 完全满足IPC-7530(回流焊及波峰焊温度曲线指导原则)和IPC/JEDEC J-STD-020C(塑封集成电路表面贴装元件的湿度/再流焊敏感性分级)对温度曲线的要求, 为生产加工提供强有力的设备与工艺保证, 为企业提供“最有价值的产品与服务”。

IPC-8(intelligent process control) series reflow oven, based on design of Genesis 8 series, adopts advanced technology and inspection standard of IPC-985X (evaluating of reflow oven), which fully satisfy the temperature profile requirement of IPC-7530 (Guidelines for Temperature Profiling for Mass Soldering Processes) and IPC/JEDEC J-STD-020C (Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices), providing powerful equipment and technology guarantee for production and processing, and the most valuable product and service for enterprises.



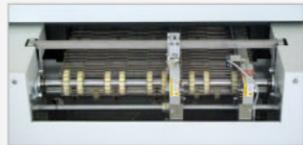
专利加热模块设计  
Patent design of heating module



专利助焊剂处理系统设计  
Patent design of flux management system



专利冷却系统设计  
Patent design of cooling system



高品质的运输装备  
High quality conveying device



## PATENT DESIGN OF FLUX MANAGEMENT SYSTEM

## 操作系统



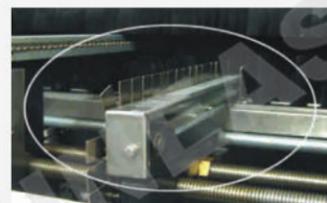
- Window视窗操作界面, 支持windows7操作系统  
Windows operation interface, support windows7
- 中英文繁体简体自由切换操作简便  
Easy switch among English, traditional & simplified Chinese characters
- 完善的温度曲线分析、存储、调用功能  
Perfect function of temperature profile analysis, storage and calls
- 操作员注册口令, 操作记录  
Operator password, operating log.
- 运行参数数字化动态显示  
Operating parameter digital dynamic display.

## OPTION

## 装配项目



双导轨PCB传送  
Double Chain Conveyor



中央支撑  
Centre Board Support



德国Esamber温度曲线测试仪  
Germany profiler

## OTHERS PROTECTION DEVICE & FUNCTION

## 其它保护装置及功能

- 温度曲线测试 Temp. profile system
- 传送及电脑UPS  
UPS for Conveyor & Computer
- 链条润滑装置(电脑控制)  
Chain Lubricator (Computer Control)
- 高低温警报 Over & Under Heat Alarm
- 传送速度异常警报 Speed Abnormal Alarm
- 导轨宽度控制手动+电动  
Conveyor Width Control System (auto/manual)
- 加热器异常检测 Heater abnormality inspection
- 热风马达异常警报 Blower motor abnormality alarm
- 电动自锁式炉体开闭 Elect. selflocked top cover
- 虚拟仿真功能 Smart Para function
- 掉板警报 Board Drop Alarm.
- 氧气浓度记录曲线(氮气型)  
O2 Control Record (N2 Type Model)
- 线路板焊接过程位置实时监控  
Realtime PCB Location Monitoring System
- 分级加热功能 Heat up by stages.
- 第三方超温保护  
The third party overheating protect
- 设备维护及焊接工艺实时帮助  
Equipment maintenance and soldering processing real time instruction

## PRODUCT FEATURES

## 产品特点

### 人性化 Humanistic

- 内嵌焊接缺陷帮助菜单及设备维护手册, 提升设备附加值  
Embed the help for soldering disfigurement and maintenance manual to enhance the machine added-value.
- 新增手动运输装置, 增加设备生产安全性  
Add manual conveying unit, to enhance the security of the machine.
- 运输系统增加自动润滑装置, 增加设备自我维护提醒功能  
Add auto-lubrication unit on conveying system to enhance the machine self-maintenance and reminding function.
- 控制系统采用PC+PLC+HMI(人机界面)方式, 增加设备安全性及可靠性  
Adopt PC+PLC+HMI on controlling system, to enhance the machine security and maneuverability.

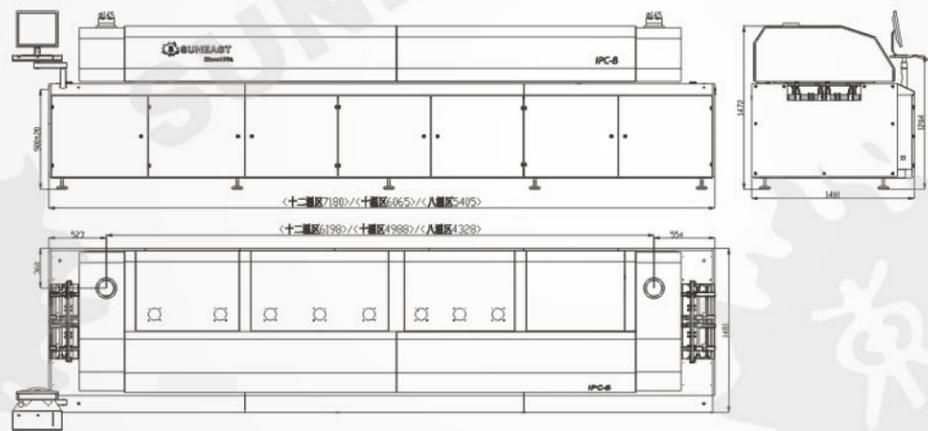
### 模块化 Modularization

- 多品种小批量生产需求的最佳选择  
Best choice for multi-variety, small batch production.
- 多种工艺技术要求的最佳适配  
Optimized configuration for multi technology request.
- 安装、调试、维护及保养方便快捷, 减少设备维护成本  
Easy installation, adjustment, maintenance, can reduce cost for maintenance.
- 可任意选择不同功率及热风对流模式适应生产需求, 可灵活选配多级助焊剂管理  
Can choose the different power and hot air convection mode freely to adapt the production request.
- 系统适应环保要求  
Can choose multilevel flux management system flexibly to adapt the request of environment protection.
- 可灵活选择风冷或水冷双冷却系统轻松实现高效柔性化  
Can realize the cooling speciality of efficiency and flexibility request.

### 高性能 High Performance

- 最佳的温度均匀性  
Exellent temperature equality.
- 优异的热效能均衡度, 实现小的温度差 ( $\Delta T$ )  
Excellent heat efficiency proportion, small temp difference ( $\Delta T$ ) can be realized.
- 最佳的温度重复精度  
Nice temp repetitive accuracy.
- 最佳的温度制程控制能力 (CPK)  
Best temperature process controlling capability. (CPK)
- 强大的环境热补偿能力及空/负载热补偿能力  
Strong circumstance heat compensation ability and non-load/load heat compensation ability.
- 高效柔性化冷却能力  
High efficient and flexible cooling ability.
- 多级过滤助焊剂管理系统  
Multilevel flux management system.

型号 Model No	IPC 808	IPC 808	IPC 808	IPC 808N	IPC 808N	IPC 808N	IPC 808A	IPC 808A	IPC 808A	IPC 810A	IPC 810A	IPC 810A	IPC 810	IPC 810	IPC 810	IPC 810N	IPC 810N	IPC 810N	IPC 810N	IPC 812A	IPC 812A	IPC 812	IPC 812	IPC 812N	IPC 812N
		双轨传输	中央支撑		双轨传输	中央支撑		双轨传输	中央支撑		双轨传输	中央支撑		双轨传输	中央支撑		双轨传输	中央支撑		双轨传输		双轨传输		双轨传输	
基板宽度尺寸(mm)	W50~440	W50~250(同时)	W50~440	W50~440	W50~250(同时)	W50~440mm	W50~440	W50~250(同时)	W50~440	W50~440	W50~250(同时)	W50~440	W50~440	W50~250(同时)	W50~440	W50~440	W50~250(同时)	W50~440	W50~440	W50~250(同时)	W50~440	W50~250(同时)	W50~440	W50~250(同时)	W50~440
Component Width		W50~500(单轨)			W50~500(单轨)			W50~500(单轨)			W50~500(单轨)			W50~500(单轨)			W50~500(单轨)			W50~500(单轨)		W50~500(单轨)		W50~500(单轨)	
基板元件高度 Component Height	以链条加长轴为基准: +30mm, -20mm Upper Max. 30mm, Lower Max. 20mm																								
温区配置 Heating Zone Structure	8温区,16加热模块 8 Heating Zone, 16 Heating Modules									10温区,20加热模块 10 Heating Zone, 20 Heating Modules									12温区,24加热模块 12 Heating Zone,24 Heating Modules						
加热区长度Heating Length	2760mm									3420mm									4140mm						
冷却方式 Cooling Type	双冷却区:水循环+外置冷机 Water Circulation+ External Chiller						双冷却区:风冷 Air Cooled						双冷却区:水循环+外置冷机 Water Circulation+ External Chiller						双冷却区:风冷Air Cooled						
工作温度范围	室温 ~ 320°C																								
温控精度Temp.Accuracy	±1°C (增强型P.I.D.控制)(Enhanced P.I.D. Control)																								
温度重复精度Temp. Reiteration Accuracy	连续生产情况下,各基板间温差 ±1°C Under continual production ,the difference of temperature on different board is±1°C																								
设备重复精度 Machine Reiteration	同等工艺设置下,不同时期所测温度曲重复性能 ±1°C Under the same technics parameter setting, the reiteration of temperature profile on different stages is±1°C																								
PCB裸板横向温差 PCB Temp. Deviation	±1°C																								
控制方式Control Type	PC+PLC控制系统 PC+PLC control system																								
操作界面Operation Interface	Windows中文繁体/English 在线自由切换 Windows Operation interface with Chinese and English Versions																								
停电保护Power cut protect	UPS及延时关机 UPS&Shutdown Delay																								
传送方向及高度 Flow Direction & Height	左→右(右→左可选); 链条传送高度: 900±20mm From L to R(R to L is option);Chain Flow Height:±20mm																								
传送方式/链条PIN长 Conveyor Type	链条/PIN长5mm+网带同步传送 Chain/Pin length 5cm + Mesh Belt Conveyor																								
调宽方式 Width modulated mode	电动+手动 Electric+ Manual																								
传送速度Conveyor Speed	0.35 ~ 1.5m/min可编程																								
电源 Power Source	AC 3Φ 5W 380V 50/60HZ																								
分段启动功率 Segment startup power	35KW	45KW	35KW	35KW	45KW	35KW	35KW	45KW	35KW	32KW	40 KW	32KW	32KW	40 KW	32KW	32KW	40 KW	32KW	43KW	51KW	43KW	51KW	43KW	51KW	
正常运行功率 Normal operation power	10 KW		10 KW	10 KW		10 KW	10 KW		10 KW	12 KW		12 KW	12 KW		12 KW	12 KW		12 KW	14 KW		14 KW		14 KW		
氮气保护装置 N2 Control Unit				有	有	有										有	有	有					有	有	
机身重量Net Weight	约2650Kg	约3000Kg	约2800Kg	约2600Kg	约3000Kg	约2800Kg	约2600Kg	约3000Kg	约2800Kg	约3000Kg	约3500Kg	约3200Kg	约3000Kg	约3500Kg	约3000Kg	约3000Kg	约3000Kg	约3000Kg	约3000Kg	约3500Kg	约3500Kg	约3500Kg	约3500Kg	约3500Kg	
排气口直径/排气量要求 Outletdiameter/ Displacement	进出口排废气口直径是Φ145; 进出口排气量分别要求是: 15m3/min ~ 20m3/min Export-emission DiameterΦ145; Displacement: 15m3/min ~ 20m3/min																								
其它 Others	温度曲线测试功能、虚拟仿真功能; 传送及电脑UPS、掉板报警功能; 电动自锁式炉体开闭、传送速度异常报警; 链条润滑装置(电脑控制)、高低温报警; 氧气浓度记录曲线(氮气型)、SPC功能、待机节能功能 Temp. Profile system, SmartPara function, UPS for Conveyor & Computer, Bard Drop Alarm, Elect. self-locked top cover, Speed Alarm, O2 Control Record (N2 Type Model), Chain Lubricator(Computer Control), Over & Under Heat Alarm																								
选项 Options	快速降温功能、氮气节能功能(氮气炉)、自动调宽功能、条码读写功能																								

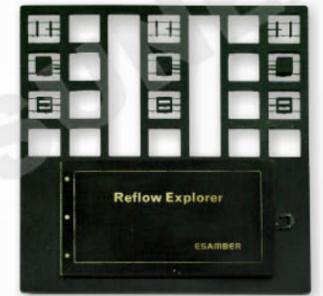


测试工具 Reflow Explorer RE3836C  
Test tool Reflow Explorer RE3836C

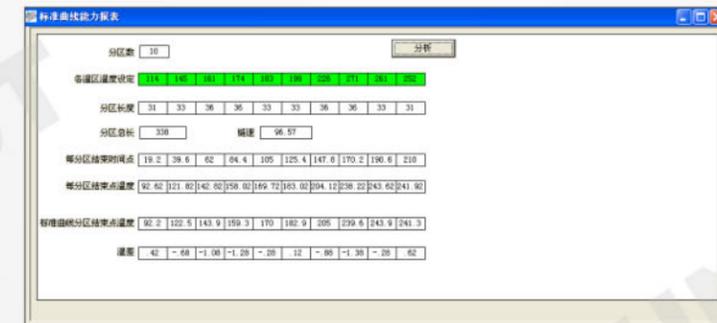
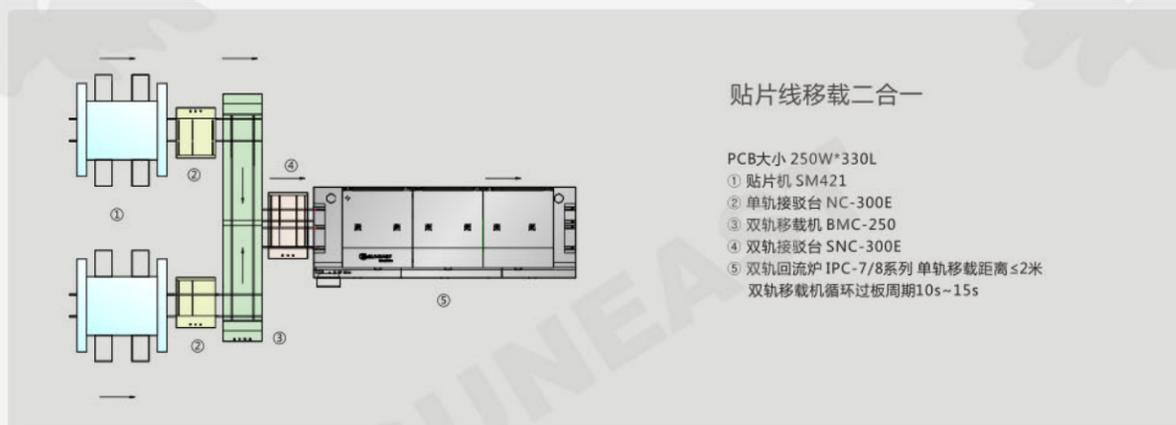
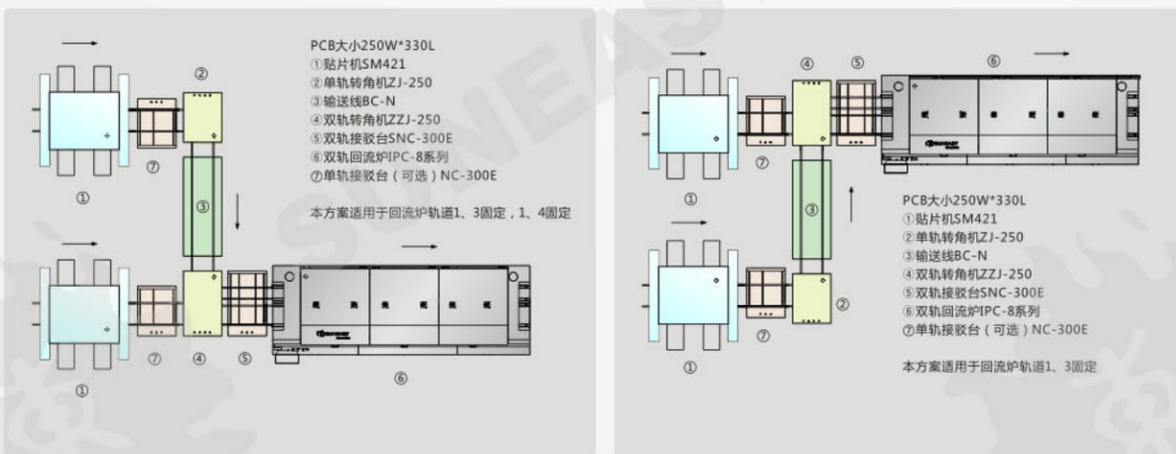
- 9测试点, 分别为:  
Nine test points, they are:
- L1, M1, R1
  - L2, M2, R2
  - L3, M3, R3

温度设定 Temperature setting

- 上炉体 Top oven shell : 114, 145, 161, 174, 183, 199, 226, 271,261,252
- 下炉体 Bottom oven shell : 114, 145, 161, 174, 183, 199, 226, 271,261,252
- 速度 : 97 CM/MIN Speed is 97 CM/MIN
- 频率 : 50HZ Frequency is 50 HZ



此炉温设定符合IPC测试标准 It is suitable for IPC test standard



一、PCBA的横截面的温差分析 Temperature difference analyses of PCBA cross section

检测分析回流炉内从导轨固定边到移动边均匀分布三点的纵向温度场异, 检测结果越小越好。

备注:

如果温度均匀性不好, 那么固定边、移动边和中心点的温度将不一致, 用测温板测试的温度曲线将不是其它位置同类元件/测试点真实温度的反映。

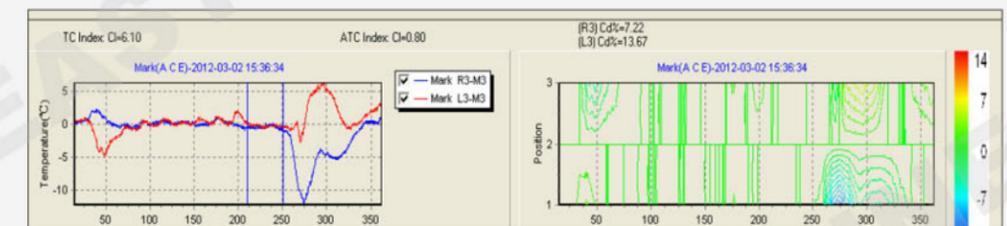
冷却区温度的均匀性如果不好, 则影响产品的焊接总时间影响降温斜率及焊料结晶状况, 从而影响产品的可靠性。

Check and analyze the vertical temperature difference of the three uniformly distributed points which are from lead rail fixed boundary to moving boundary.

Remarks

The temperatures of fixed boundary, moving boundary and central point are different if the temperature uniformity is not good. The temperature profile which tested by thermo detector is not the real temperature of the same elements/test points in other positions.

If the temperature uniformity of cooling zone is not good, it will effect the products' soldering total time, temperature cooling slope and solder crystal status, and then will effect the reliability of the product.



热均匀分析CI=0.8°C Heat uniformity analyze CI=0.8°C

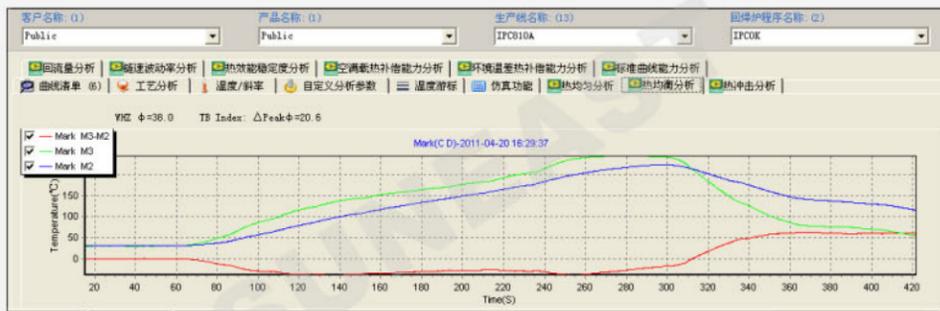
## 二、热效能均衡度评测 Evaluation of heat efficiency equality

检测分析不同热容大小的标准模块之间温度的差异，反映回流炉加热速度的能力，差异越小越好。

如果热效能均衡度较大，不同大小（热容）的组件，如0603、QFP和BGA等在焊接过程中的温度相差会比较大，造成温度曲线调试困难甚至无法调试出满足要求的温度曲线设定。

Check and analyze the temperature difference of standard module with different heat capacity, and reflect the heating rate ability of reflow oven. The less the difference is, the better the effect is.

If the heat efficiency equality is not big, During soldering process, Temperature difference of different heating capacity parts, such as 0603, QFP and BGA will be big, it is difficult to adjust temperature profile, even it's impossible to adjust required temperature profile setting.



热均衡 Heat efficiency 20.6

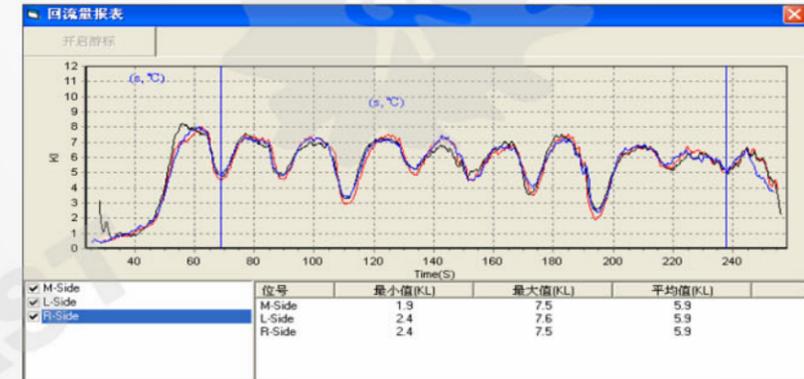
## 三、热效率评测 Heatefficiency evaluation

评测热风气流的可调范围，评价不同热风速率情况下的炉体热效率，同时还能确认默认风扇设定是否落为最佳范围。根据经验，对于SMT工艺过程，对流量的最佳范围是4.5-6.5之间。

备注：  
回流炉使用热气流回流方式对产品进行加热，其回流程度的强弱将直接影响到焊接质量。只有合适的全程回流量才能获得良好的焊接质量。  
通过回流量分析直接可以看出加热模块的热补偿能力及机械结构设计缺陷。

Test the adjustable range of hot air stream, test the oven hot efficiency with different hot air speed rate; At the same time, check whether the tolerant fan setting is in the best range or not. For SMT technics process, the best range of flow is between 4.5 and 6.5 according to experiences.

Remarks:  
Reflow oven applies air hot stream to heat the product, the thickness of the reflow degree will effect the soldering quality directly. The machine will achieve good soldering quality only by suitable whole process reflow quantity.  
The heat compensation ability and mechanical structure design defect can be analyzed directly by reflow quantity.



风流量 Wind flow =5.9KL

## 四、热补偿能力测评 Evaluation of heat compensation ability

### 环境热补偿能力 Environmental Heat compensation ability

检测分析回流焊设备对环境温度差异的热效能补偿能，这个参数代表回流炉抗干扰能力，检测结果越小越好。如果热补偿能力不足，则在环境温度发生变化时，例如白夜班，夏冬季节，炉子入口距离空调口较近等状况下，因为产品初始温度不同，会造成温度曲线整体偏移，甚至有超出规格的风险，从而无法保证焊接质量。

Check and analyze the environmental heat compensation ability of the reflow oven equipment. This parameter is the reflow oven capacity of resisting disturbance. The better the test result is smaller. If the heat compensation ability is not enough, because the product initial temperature is different, it will cause temperature profile overall deviation, even beyond the specification, then it can't promise the soldering quality when the environmental temperature changes, for example, different work shift, different weather and the distance between oven entrance and air condition is too near.



热效能稳定度 Heat efficiency stability Sd=9.5%

## 空满载能力 Idle and full load ability

检测分析标准低热负载和标准高热负载时的加热能力和热补偿能力，这个参数代表回流炉带负载的能力，温度曲线的差异度越小越好。如果空/负载能力不足，则炉子的负载能力将较低，在炉子内同时焊接很多片板，板子间距比较小时，容易造成局部冷焊等不良状况。

Check and analyze the heating ability and heat compensation ability when the machine is in standard low-heat load and in standard high-heat load. This parameter is the load ability of reflow oven. The better the smaller difference of temperature profile.

If the idle/load ability is not enough, the load ability of oven is low. It is easy to cause badness, such as local cold welding when you solder many pin plates in the oven at the same time and the distance between the plates are narrow.



空满载能力 Idle full load ability Id=30.35%

## 五、热稳定性测评 Heat stability evaluation.

全程分析温度曲线稳定性，同时监测分析每个加热区的热稳定性，检测结果越小越好。

备注：设备短期稳定度分析；

如果热稳定性较低，则产品在焊接过程中的实际温度将有较大差异，测温板测试的温度曲线将不具备代表性，回流炉内的实际温度将会有较大变化。

Analyzing the overall temperature profile stability, at the same time, monitor and analyze the heat stability of every heating zone. The better the smaller result.

Remarks

Analyze the short stability of device

If the heat stability is low, it will cause big difference of actual temperature during soldering, the temperature profile which was tested by thermo detector is not representative, the actual temperature in the reflow oven will have big change.



CPK (左 left) = 3.56

CPK (中 middle) = 3.13

CPK (右 right) = 4.23

## AGGREGATIVE INDICATOR LEVER

## 综合指标水平

各项性能指标 Each performance indicator	热均匀能力CI Heat uniformity ability CI	热均衡能力φ Heat equality ability φ	风流量性能ψ Wind flow ability ψ	热效能稳定度Sd Heat efficiency stability Sd	空满载能力Ld Idle full load ability Ld	重复精度CPK Repeat accuracy CPK
标准值 Standard value	I<3°C, II<6°C, III<9°C	I<22, II<28, III>28	I:4.5-6.5, II:3.0-7.5, III:2.0-8.5	I<25% II<50% III<100%	I<50% II<75% III<100	I:>1.67 II:1.33~1.67 III:1.0~1.33
IPC-8	0.8°C	20.6°C	5.9KL	9.5%	30.35%	>1.67

## ESAMBER REFLOW EXPLORER

## Esamber 回流炉性能测试仪

该产品主要用于回流焊设备状况的检测，依据检测数据，分析各项工艺指标是否适合生产现有的产品，大量减少因设备能力不足而造成的不良。



Reflow Explorer 应用:

### Esamber R9E3测试仪技术参数:

型号	Esamber R9E3
尺寸(mm)	152 (L) × 110 (W) × 17 (H)
通道数	9通道温度记录 3通道扩展记录(回流量、链速等)
热电偶型号	K型
测温范围	0~800°C
采样频率	0.1~400秒
精度	±0.5°C
分辨率	0.1°C
数据接口	通用USB传输
电池	可充电电池
软件系统	Microsoft Windows 2000、XP
语言	德文、英文、简体中文、繁体中文

### Reflow Explorer 特性:

热效能均匀度分析  
热冲击度分析  
热效能均衡度分析  
回流量分析  
链速波动率分析  
SPC性能分析

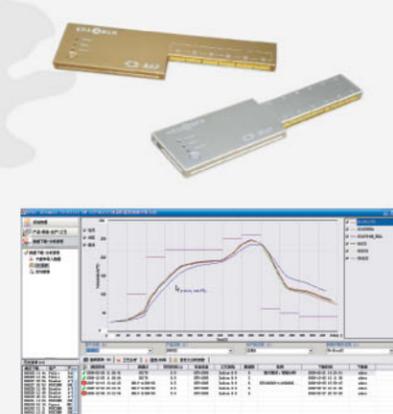
Profile工艺分析  
温度/斜率分析  
自定义参数分析  
温度游标分析  
仿真功能分析

## ESAMBER R PROFILER

## Esamber 温度曲线测试仪

### Esamber R 系列技术指标:

型号	R6P	R10T	R12T	R16T	R24H	R32H
尺寸 (mm)	221x60x10	221x60x10	221x60x10	255x60x10	219x60x20	251x60x20
通道数量	6	10	12	16	24	32
采样频率	0.1秒~400秒可调					
精度	±0.5°C					
分辨率	0.1°C					
测温范围	-100~800°C					
数据点存储	每通道32,000点数据					
数据接口	通用USB接口					
下载速度	1000点/秒(快速下载)					
测温仪启动方式	启动/停止单按键操作, 温度自动触发					
电池	耐高温可充电电池, 在下载数据的同时也在进行充电					
热电偶	K型					
软件系统	Microsoft Windows 2000、XP					
软件语言	德文、英文、简体中文、繁体中文					



EPRs 分析软件

### 专业、易用的分析软件

- 对象式数据库管理，智能数据搜索，查找不再麻烦
- 现场式SMT焊锡工艺管理，所见即所需
- 工艺参数自动分析，智能判断，所见即所得
- 自动SPC统计分析
- 人性化界面，快速掌握
- 德文、英文、简体中文、繁体中文软件语言



自主品牌产品 | Own Brand Products

研发、生产自主品牌产品，拥有SMT全套解决方案，包括锡膏印刷机、韩国三星贴片机、无铅热风回流炉、AOI台式外观检测机及周边设备系列。

R & D combined with ability to manufacture its own branded products, own SMT total solution. Including Screen Printer, Chip Mounter, Lead Free Hot-air Reflow Oven, AOI Desktop Appearance Test Machine, as well as Peripheral Series.



生产加工实力 | Production Capability

- 大型钣金加工设备
- 精密设备加工制造中心
- 强大的加工团队
- 自动喷粉涂装
- 电镀加工
- Large sheet metal processing equipment
- Precision equipment manufacturing center
- Automatic powder coating
- Electroplating tech
- Powerful processing work team



战略合作 | Strategic Cooperation

通过分销与技术合作形式进行战略合作，包括为韩国三星分销多功能元件贴装设备，与哈工大、中科院、北京汉王科技等进行技术合作与联合开发新型产品。在智能化装备领域不断拓展和创新。

To enter into strategic partnership by distribution and technical cooperation, including distribution of Samsung multi-function surface mount systems, to cooperate in technologies with Harbin Institute of Technology, Shenzhen Institute of Advanced Technology Chinese Academy of Science, Beijing HanWang Technology Group etc., jointly to develop new products. The Sun East has continuously expands and promotes his new areas of high technology in the field of intelligent products.



服务策略 | Service Strategy

立足于智能化装备领域，以产品设备为基础向客户提供全面解决方案及软硬件供应。重视售前售后服务，以推行绿色环保服务方针为己任。

Based on the field of intelligent equipment, the Sun East is as the software and hardware supplier to provide total solutions. Pay much more attention to pre & after-sales services, implement with green service environmental system.

- 国家级高新技术企业
- 重合同守信用企业
- 深圳市宝安区首届技术创新奖
- 宝安区科技工作先进单位
- 深圳深港生产力基地有限公司 创会会员
- 中国电子专用设备工业协会 理事单位
- 中国机车工业协会 会员单位
- 深圳市钣金加工行业协会 会员单位
- 香港SMT美国表面安装技术协会 副会长单位
- 深圳市加工贸易SMT协会 副会长单位
- 2003, 2005, 2006年荣获香港工业奖
- 第十届中国国际高新技术成果交易会  
—— 成果转化优秀项目奖

- "National High Tech Enterprise" award
- "A Trustworthy Enterprise" award
- The First Technology Innovation Award of Bao'an, Shenzhen
- Advance Scientific and Technology Work Units of Bao'an, Shenzhen
- Founding Member of Shenzhen SZ-HK Productivity Foundation Co., Ltd
- Special Equipment Units of China Electronic Production Equipment Industry Association
- Member of China Association of Automobile Manufacturers
- Member of Shenzhen Sheet Metal Processing Industry Association
- Vice President Unit of SMT Association of America in Hong Kong
- Vice President Unit of Shenzhen Chamber of Investment
- 2003, 2005 and 2006 Hong Kong Industries Award
- "Award for Industrialize Excellence" in the 10<sup>th</sup> China High Tech Fair

合作伙伴 PARTNERS



荣誉客户 HONOURABLE CUSTOMERS

